Pch -30V -3.5A Power MOSFET

V <sub>DSS</sub>	-30V
R <sub>DS(on)</sub> (Max.)	50mΩ
I <sub>D</sub>	±3.5A
$P_D$	1.25W

# ● Features

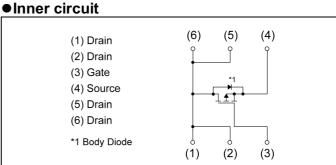
- 1) Low on resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small Surface Mount Package (TSMT6).
- 4) Pb-free lead plating; RoHS compliant

### ●lnı

Outline
SOT-457T

SC-95

TSMT6



Packaging specifications

or dokaging opcomodions							
	Packing	Embossed Tape					
	Reel size (mm)	180					
Туре	Tape width (mm)	8					
	Basic ordering unit (pcs)	3000					
	Taping code	TR					
	Marking	JR					

# Application

Switching

## ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	$V_{DSS}$	-30	V
Continuous drain current	I <sub>D</sub> *1	±3.5	Α
Pulsed drain current	I <sub>DP</sub> *2	±12	А
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Avalanche current, single pulse	I <sub>AS</sub> *3	-3.5	Α
Avalanche energy, single pulse	E <sub>AS</sub> *3	9.0	mJ
Power dissipation	P <sub>D</sub> *4	1.25	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Parameter  Charmal registeres, junction, ambient	Symbol	Values			l limit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	R <sub>thJA</sub> *4	1	100	1	°C/W

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Symbol	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = -1mA$		-30	-	-	V	
Breakdown voltage	$\Delta V_{(BR)DSS}$	I <sub>D</sub> = -1mA	-	-22	_	mV/°C	
temperature coefficient	ΔT <sub>j</sub>	referenced to 25°C				11177 0	
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS}$ = -30V, $V_{GS}$ = 0V	ı	ı	-1	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS}$ = ±20V, $V_{DS}$ = 0V	ı	1	±100	nA	
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = -1mA$	-1.0	-	-2.5	V	
Gate threshold voltage	$\Delta V_{GS(th)}$	I <sub>D</sub> = -1mA		2.0		m\ //°C	
temperature coefficient	$\Delta T_j$	referenced to 25°C	- 2.9		-	mV/°C	
Static drain - source	D *5	$V_{GS} = -10V, I_D = -3.5A$	-	38	50	0	
on - state resistance	R <sub>DS(on)</sub> *5	$V_{GS} = -4.5V, I_D = -3.5A$	-	54	70	mΩ	
Forward Transfer Admittance	Y <sub>fs</sub>  *5	V <sub>DS</sub> = -5V, I <sub>D</sub> = -3.5A	3.2	-	-	S	

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $\simeq$  1mH,  $V_{DD}$  = -15V,  $R_G$  = 25 $\Omega$ , STARTING  $T_{ch}$  = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Mounted on a ceramic boad (30×30×0.8mm)

<sup>\*5</sup> Pulsed

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Darameter	Symbol	Conditions	Values			Unit	
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Offic	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	475	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = -15V	-	85	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	65	-		
Turn - on delay time	t <sub>d(on)</sub> *5	V <sub>DD</sub> ≈ -15V,V <sub>GS</sub> = -10V	-	8	-		
Rise time	<b>t</b> r*5	I <sub>D</sub> = -1.8A	1	12	1	no	
Turn - off delay time	t <sub>d(off)</sub> *5	R <sub>L</sub> ~ 8.2Ω		40	-	ns	
Fall time	<b>t</b> <sub>f</sub> *5	$R_G = 10\Omega$	-	20	-		

# ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Davamatav	Cymahal	Conditions		Values			l limit
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total gate above	O *5		V <sub>GS</sub> = -10V	-	10	-	
Total gate charge	$Q_g^{*5}$	$V_{DD} \simeq -15V$ $I_D = -3.5A$		-	5.2	-	<b>"</b> C
Gate - Source charge	Q <sub>gs</sub> *5		V <sub>GS</sub> = -4.5V	-	1.6	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5			-	1.9	-	

## ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Darameter	Symbol	Conditions	Values			Unit	
raiametei	Parameter Symbol Conditions		Min.	Тур.	Max.	Offic	
Continuous forward current	I <sub>S</sub> *1	T = 25°C	-	-	-1.0	Α	
Pulse forward current	I <sub>SP</sub> *2	T <sub>a</sub> = 25°C	-	-	-12	Α	
Forward voltage	V <sub>SD</sub> *5	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1.0A	-	-	-1.2	V	

Fig.1 Power Dissipation Derating Curve

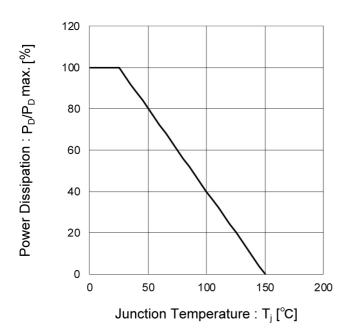
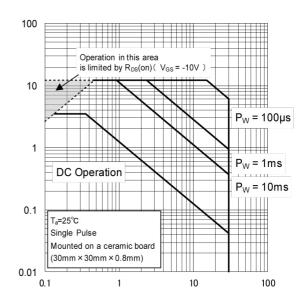


Fig.2 Maximum Safe Operating Area



Drain Current: -l<sub>D</sub> [A]

Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

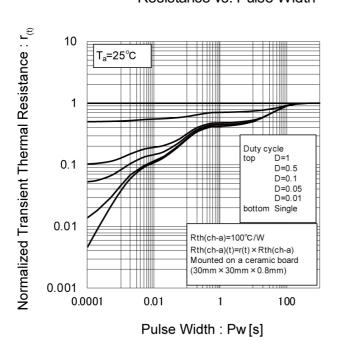
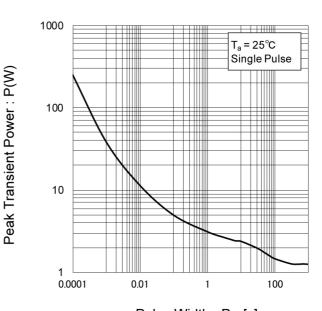


Fig.4 Single Pulse Maximum Power dissipation



Pulse Width : Pw [s]

Drain Current : -I<sub>D</sub> [A]

Drain-Source Breakdown Voltage: -V<sub>(BR)DSS</sub> [V]

## Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

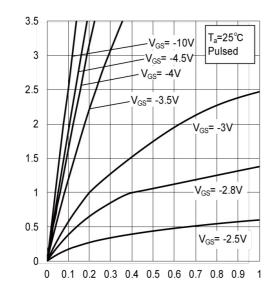
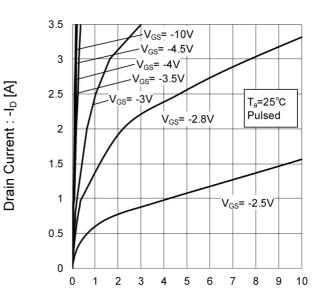
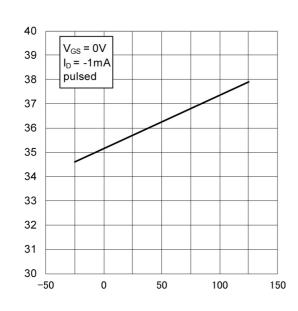


Fig.6 Typical Output Characteristics(II)



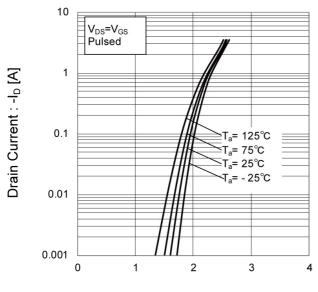
Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.7 Breakdown Voltage vs. Junction Temperature



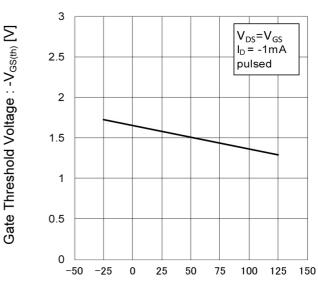
Junction Temperature : T<sub>i</sub> [°C]

Fig.8 Typical Transfer Characteristics



Gate - Source Voltage : -V<sub>GS</sub> [V]

Fig.9 Gate Threshold Voltage vs. Junction Temperature



Junction Temperature : T<sub>j</sub> [°C]

Fig.10 Transconductance vs. Drain Current

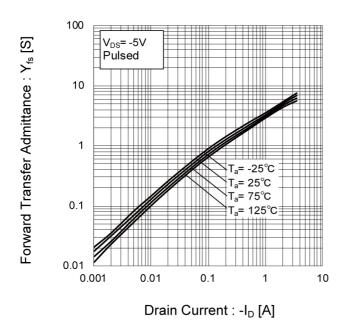


Fig.11 Drain Current Derating Curve

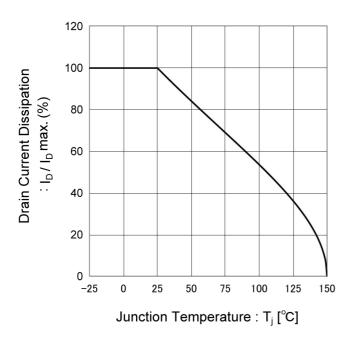
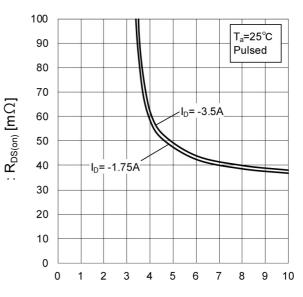


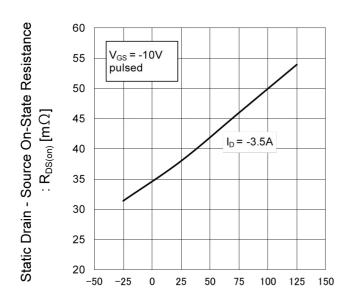
Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



Static Drain - Source On-State Resistance

Gate - Source Voltage : -V<sub>GS</sub> [V]

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



Junction Temperature : T<sub>j</sub> [°C]

7/11

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

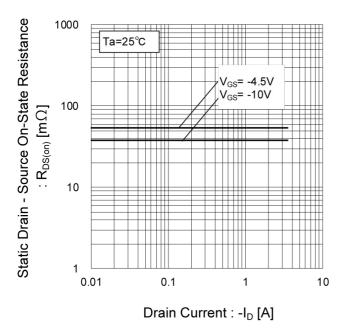


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

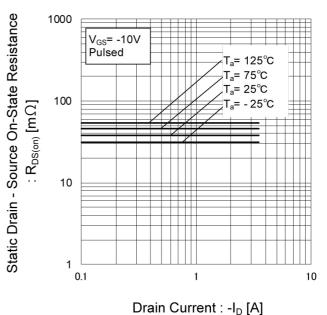
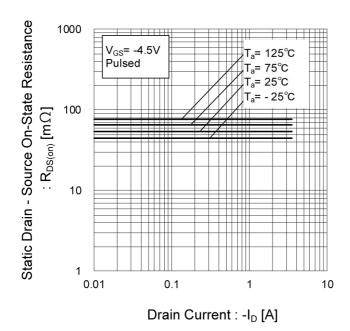
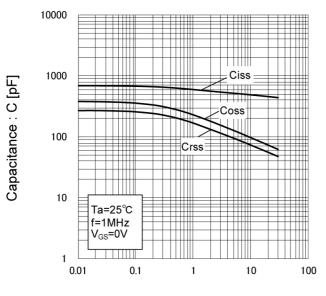


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)



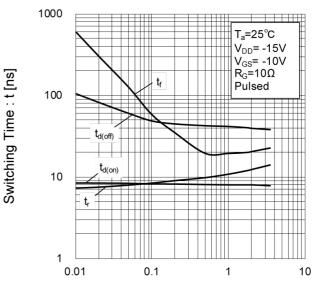
ROHM

Fig.17 Typical Capacitance vs. Drain - Source Voltage



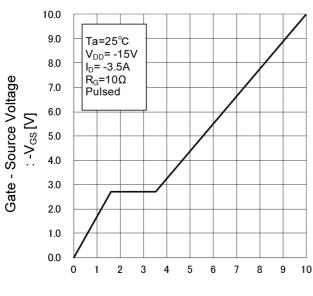
Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.18 Switching Characteristics



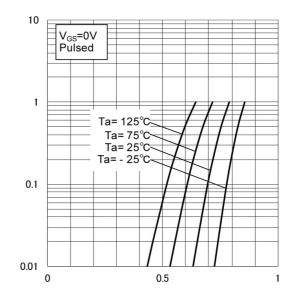
Drain Current: -ID [A]

Fig.19 Dynamic Input Characteristics



Total Gate Charge : Q<sub>q</sub> [nC]

Fig.20 Source Current vs. Source Drain Voltage



Source - Drain Voltage : -V<sub>SD</sub> [V]

Source Current : -I<sub>s</sub> [A]

## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

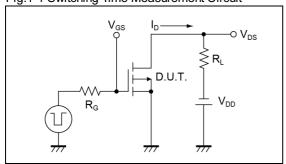


Fig.2-1 Gate Charge Measurement Circuit

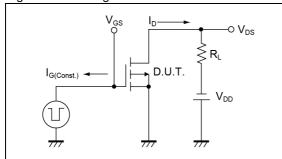


Fig.3-1 AVALANCHE MEASUREMENT CIRCUIT

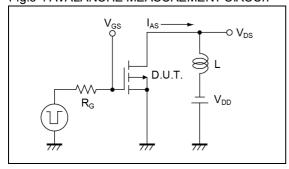


Fig.1-2 Switching Waveforms

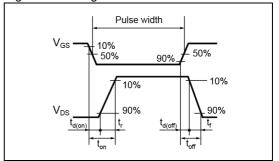


Fig.2-2 Gate Charge Waveform

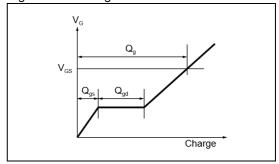
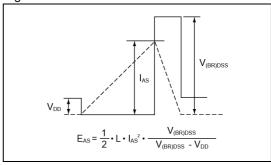
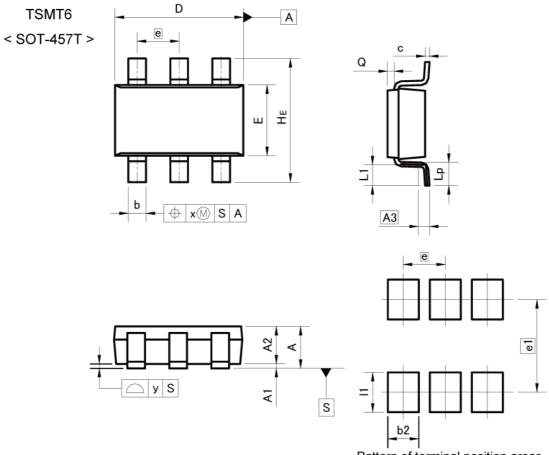


Fig.3-2 AVALANCHE WAVEFORM



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1-	1.00	ı	0.039
A1	0.00	0.10	0.000	0.004
A2	0.75	0.95	0.030	0.037
A3	0.3	25	0.0	10
b	0.35	0.50	0.014	0.020
С	0.10	0.26	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.9	95	0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.05	0.25	0.002	0.010
х	_	0.20	-	0.008
У	_	0.10	_	0.004

DIM	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
b2		0.70	_	0.028
e1	2.10		0.0	83
11	\	0.90	-	0.035

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CL ACCIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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